SL Modular Connector System

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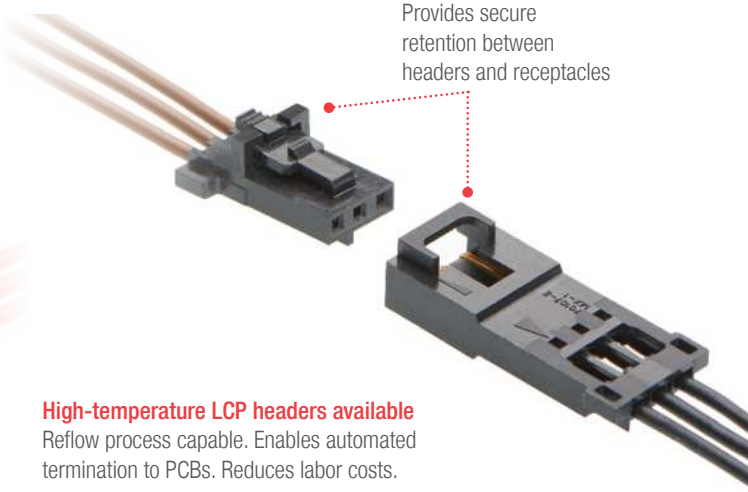
With its large number of options and configurations, SL Modular Connectors and Assemblies deliver ideal wire-to-wire solutions and its varying PCB termination methods, including reflow process capable versions, support a range of wire-to-board applications

Features and Advantages

Two independent points of contact
Offers redundant, secondary current paths for long-term electrical performance and reliability

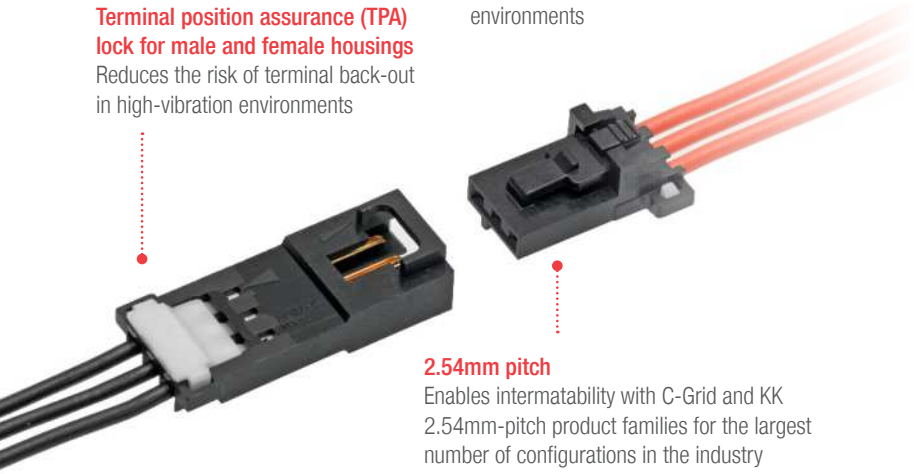
Low-profile, stackable housing, vertical and right-angle headers
Provides design flexibility with or without panel mounting

Positive lock
Provides secure retention between headers and receptacles



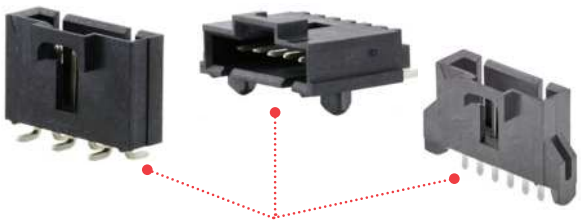
Connector position assurance (CPA) lock
Ensures wire-to-wire and wire-to-board mating interface will not disengage in high-vibration environments

Terminal position assurance (TPA) lock for male and female housings
Reduces the risk of terminal back-out in high-vibration environments



High-temperature LCP headers available
Reflow process capable. Enables automated termination to PCBs. Reduces labor costs.

2.54mm pitch
Enables intermatability with C-Grid and KK 2.54mm-pitch product families for the largest number of configurations in the industry



High-temperature headers available, made with liquid crystal polymer (LCP)
Reflow process capable. Enables automated termination to PCBs. Reduces labor costs.

Applications

Consumer
- Computer Peripherals
- Copiers
- HVAC Equipment
- Modems
- Printers
- Scanners

Automotive
- Airbag Sensors
- Interior Lighting
- Sound Systems
- Steering Controls

Medical
- Panel Displays on Portable Medical
- Dental Equipment
- Breathing Machines



Automotive Interior Lighting and Sound System



Copiers and Printers



Portable Diagnostics

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Specifications

REFERENCE INFORMATION
Packaging: Tape-and-reel, tube
UL File No.: E29179
CSA File No.: LR19980
Designed In: Millimeters
RoHS: Yes
Halogen Free: No
Glow Wire Compliant: No

ELECTRICAL
Voltage (max.): 250V
Current (max.): 3.0A
Contact Resistance (max.): 15 milliohms
Dielectric Withstanding Voltage (min.): 600V AC
Insulation Resistance (min.): 10000 Megohms

MECHANICAL
Mating Force (min.): 45N
Unmating Force (min.): 15N
Durability (min.): 25 (Tin) 50 (Gold)

PHYSICAL
Housing: Glass-filled polyester
High-Temp Housings: Liquid Crystal Polymer (LCP)
Contact: Brass
Plating:
Contact Area — Matte tin or select gold
Solder Tail Area — Matte tin
Underplating — Nickel
Operating Temperature: -40 to +105°C

Ordering Information

Tape-and-Reel Packaging Versions

Order No.	Component	Circuits	Plating	Poles
74099-06XX	Wire-to-Board Headers, Vertical SMT	3 through 12	Tin	5-Pole Power
74099-06YY			15µ" Gold	
74099-06ZZ			30µ" Gold	
15-91-6XX9	Wire-to-Board Headers, Right Angle SMT	2 through 25	Tin	
15-91-7XX0			15µ" Gold	
15-91-7XX1		2 through 12	30µ" Gold	

XX: Replace XX with desired circuit size
YY: Replace YY with desired circuit size +20 (e.g.: 3 circuit = 74099-0623)
ZZ: Replace ZZ with desired circuit size +40 (e.g.: 3 circuit = 74099-0643)

Tube Packaging Versions

Series No.	Component	Circuit Sizes
70066, 70107	Crimp Housings	2 to 25
70021, 70058, 71851	Crimp Terminals	22 to 32 AWG
70541, 70543, 70545, 70551, 70553, 70555, 70634, 74095, 74099, 87898	PCB Headers	2 to 25
73838	Female TPA Locks	2 to 8
70400, 70475	IDT Assemblies	2 to 25
70013, 70022	Clips and Modular Branches	2 to 50

Series No.	Component	Wire Gauge
70021, 70058, 71851	Crimp Terminals	22 to 32 AWG

High-Temperature Headers That Are Reflow Process Capable

Series No.	Type	Orientation	Circuit Sizes
171971	Through Hole	Vertical	2 to 25
171972	Through Hole with Pegs		
171974	Through Hole	Right-Angle	
171975	Through Hole with Pegs		
171973	SMT	Vertical	
171976		Right-Angle	
171977	SMT with Pegs	Right-Angle	

www.molex.com/link/slmodular.html

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